

May 15, 2024

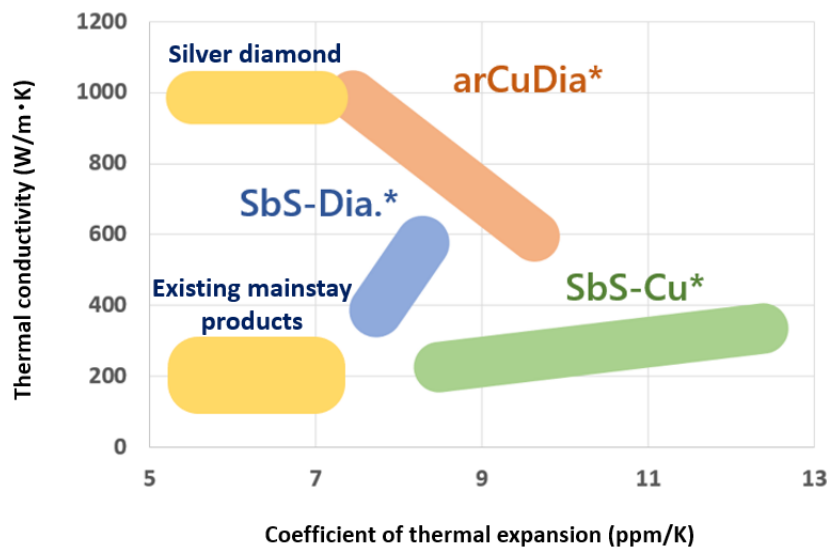
To whom it may concern:

Company: TECNISCO, LTD.
Representative: Keizo Sekiya, Chairman and Chief Executive Officer
(Code No.: 2962, Tokyo Stock Exchange, Standard Market)
Contact: Masayuki Aihara, Executive Director and Chief Financial Officer
(Phone: +81-3-3472-6963)

Basic Agreement for Business Alliance with THE GOODSYSTEM CORP.

TECNISCO, LTD. (Headquarters: Shinagawa-ku, Tokyo; Chairman & CEO: Keizo Sekiya; hereinafter referred to as 'the Company') has reached a basic agreement with THE GOODSYSTEM CORP. (Headquarters: Ansan-si, Gyeonggi-do, South Korea; President & CEO: Matthew Cho; hereinafter referred to as 'TGS') to expand its product lineup and strengthen its development capabilities in the high-performance heatsink field.

By incorporating TGS's product portfolio with our proprietary material, Silver diamond (diamond composite material), which boasts exceptionally high thermal conductivity, we aim to broaden the coverage of market needs for high-performance heatsinks.



*arCuDia, SbS-Dia. and SbS-Cu are products of TGS

While the specific details of the partnership will be finalized in the future, we anticipate activities such as mutual customer referrals, sharing of marketing information, and leveraging each other's technologies.

Through this partnership with TGS, we will leverage the insights gained and connections established to further expand the sales of high-performance heatsink products, including Silver diamond.

【Overview of THE GOODSYSTEM CORP.】

Headquarters: Ansan-si, Gyeonggi-do, South Korea

CEO/President: Matthew Cho (Ph.D. in Engineering from Tohoku University)

CTO/Vice President: Liam Lee (Ph.D. in Engineering from Tohoku University)

Established: May 31, 2016

Business Activities: Manufacturing and sales of high-performance metal composite heat dissipation materials and heat dissipation substrates for semiconductor packages

URL: <http://thegsystem.co.kr/>

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